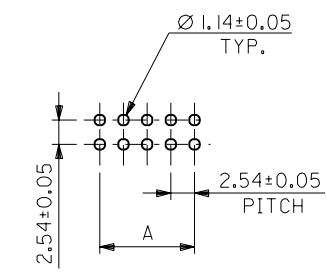


注記 NOTES

- 材質 MATERIAL
ハウジング : ガラス入りPBT UL94V-0 色:黒
HOUSING : G.F.PBT UL94V-0 COLOR:BLACK
ピン : リン青銅
PIN : PHOSPHOR BRONZE
- メッキ仕様 PLATING
ピン : 接点部 金メッキ 0.38 μ m MIN.
CONTACT AREA GOLD 0.38 μ m MIN.
半田付け部 半田メッキ 1.9 μ m MIN.
SOLDER TAIL AREA TIN-LEAD 1.9 μ m MIN.
下地メッキ ニッケルメッキ 1.27 μ m MIN.
UNDER-PLATING NICKEL 1.27 μ m MIN.

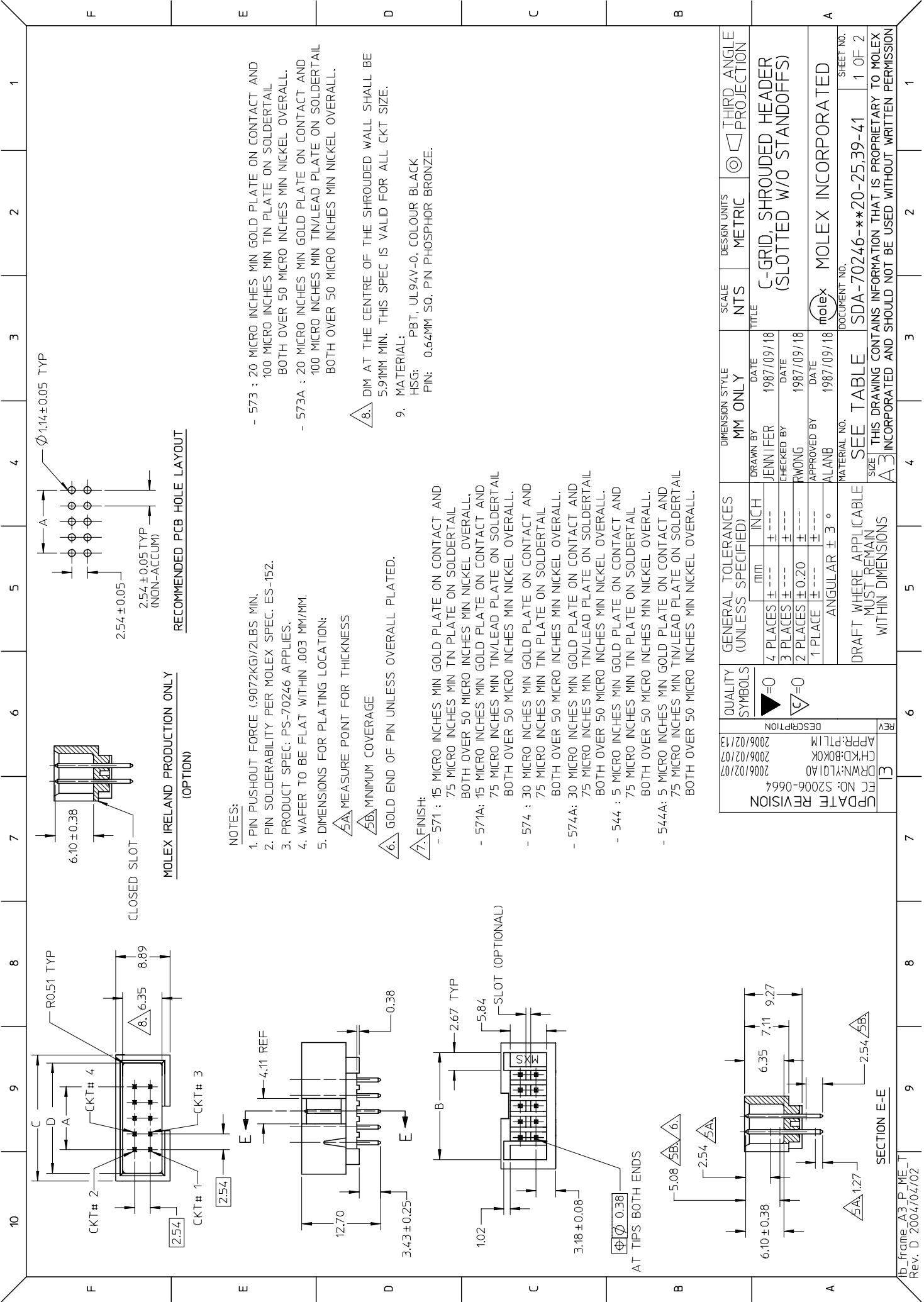
- 3. メッキ厚測定位置
MEASURING POINT FOR PLATING THICKNESS
- 4. メッキ範囲
PLATING AREA
- 6. ピン先端にて測定
MEASURE PIN TIP END



68.58	71.12	68.07	60.96	A-70246-5021	50
D	C	B	A	ENG. No.	種数 CKT. SIZE

材料 MATERIAL 注記参照 SEE NOTES		モレックス MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH 注記参照 SEE NOTES		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE —		TITLE 名称 ASSY,C-GRID,SHROUDED HEADER (SLOTTED WITHOUT STANDOFFS)	
被覆外径 INS. RANGE —		DWG. NO. SDA-70246-*****	
DRAWN BY CHK'D BY		REV 0	
APPR'D BY DATE		SCALE 2 - 1	
記号 LTR 変更内容 REVISION RECORD		DR. CHK. 日付 DATE	
一般公差 GENERAL TOLERANCES		記号 LTR 変更内容 REVISION RECORD	

角度 ANGLE	$\pm 30^\circ$
30 以上 OVER	+0.3
10 以上 30 未満 UNDER	+0.25
10 未満 UNDER	+0.2



MOLEX IRELAND PRODUCTION ONLY (OPTION)

RECOMMENDED PCB HOLE LAYOUT

NOTES:

1. PIN PUSHOUT FORCE (.9072KG)/2LBS MIN.
2. PIN SOLDERABILITY PER MOLEX SPEC. ES-152.
3. PRODUCT SPEC: PS-70246 APPLIES.
4. WAFER TO BE FLAT WITHIN .003 MM/MM.
5. DIMENSIONS FOR PLATING LOCATION:
 - 5A MEASURE POINT FOR THICKNESS
 - 5B MINIMUM COVERAGE
6. GOLD END OF PIN UNLESS OVERALL PLATED.
7. FINISH:
 - 571 : 15 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 571A : 15 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN/LEAD PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 574 : 30 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 574A : 30 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN/LEAD PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 544 : 5 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 544A : 5 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN/LEAD PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
8. DIM AT THE CENTRE OF THE SHROUDED WALL SHALL BE 5.9MM MIN. THIS SPEC IS VALID FOR ALL CKT SIZE.
9. MATERIAL:
 - PBT, UL94V-0, COLOUR BLACK
 - HSG: 0.64MM SQ. PIN PHOSPHOR BRONZE.

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4 PLACES $\nabla=0$ 3 PLACES $\nabla=0$ 2 PLACES $\nabla=0$ 1 PLACE $\nabla=0$ ANGULAR $\pm 3^\circ$ DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MM ONLY NTS TITLE C-GRID, SHROUDED HEADER (SLOTTED W/O STANDOFFS)	DRAWN BY JENNIFER CHECKED BY RWONG APPROVED BY ALANB	DATE 1987/09/18 DATE 1987/09/18 DATE 1987/09/18	DOCUMENT NO. SDA-70246-20-25,39-41 SHEET NO. 1 OF 2	MOLEX INCORPORATED

